



(19)

(11) Publication number: 2000022071

Generated Document.

PATENT ABSTRACTS OF JAPAN

(21) Application number: 10182943

(51) Intl. Cl.: H01L 25/00 H01L 23/32 H05K 3/34

(22) Application date: 29.06.98

(30) Priority:

(43) Date of application
publication: 21.01.00(84) Designated contracting
states:

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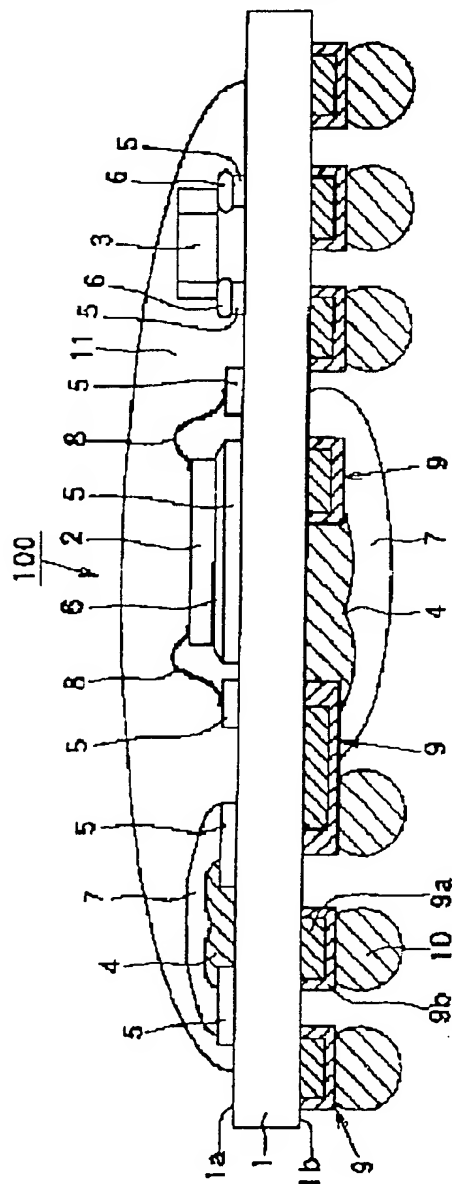
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(57) Abstract:

PROBLEM TO BE SOLVED: To provide a structure related to an MCM(Multi-Chip Module) with an interposer that can be lessened in size, wherein the MCM is composed of the interposer, electric elements formed on the surface of the interposer, and pad electrodes formed on the backside of the interposer and electrically connected to the outside through solder bumps joined to the pad electrodes.

SOLUTION: An MCM 100 is equipped with an interposer 1, where a semiconductor chip 2, a component 3 such as a capacitor or the like, film resistors 4 of LaB6 or the like are provided to the surface 1a of the interposer 1, and pad electrodes 9 and bumps 10 bonded to the pad electrodes 9 are provided in the backside 1b of the interposer 1. At this point, some of the resistors 4 are each provided between the pad electrodes 9 on the backside 1b of the interposer 1 so as to lessen the rear surface 1b in mounting area.



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